PART NUMBER DATA SHEET

EMRB82B-32.768K

Click part number to visit Part Number Details page

Ecliptek

REGULATORY COMPLIANCE (Data Sheet downloaded on Aug 3, 2020)

Lead Free COMPLIANT | EU RoHS 2011/65 + 2015/863 COMPLIANT | China RoHS COMPLIANT | REACH 191 SVHC COMPLIANT

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DRC CONFLICT FREE

ITEM DESCRIPTION

MEMS Clock Oscillators LVCMOS (CMOS) 2.5Vdc 4 Pad 0.8mm x 1.5mm Chip Scale Package (CSP) 32.768KHz ±75ppm over -10°C to +70°C

ELECTRICAL SPECIFICATIONS

Nominal Frequency	32.768KHz
Frequency Tolerance/Stability	±75ppm Maximum over -10°C to +70°C (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, and Output Load Change)
Frequency Tolerance	±20ppm Maximum (Measured at 25°C ±2°C, at Vdd=2.5Vdc, Post Reflow, with board level underfill)
Aging at 25°C	±1ppm Maximum First Year
Supply Voltage	2.5Vdc ±10%
Core Operating Current	0.9µA Typical (at 25°C), 1.3µA Maximum
Output Stage Operating Current	0.065µA/Vpp Typical, 0.125µA/Vpp Maximum
Input Current	1.1µA Typical (at 25°C), 1.6µA Maximum (No Load, Nominal Vdd)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH = -10µA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL = +10µA)
Rise/Fall Time	100nSec Typical, 200nSec Maximum (Measured from 10% to 90% of waveform)
Duty Cycle	50 ±2(%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Period Jitter (RMS)	35nSec Typical (Measured at 25°C)
Power Supply Ramp	100mSec Maximum (Measured at 0Vdc to 90% of Vdd)
Start Up Time	180mSec Typical, 300mSec Maximum (at 25°C) 450mSec Maximum (over Operating Temperature Range) (Measured at Nominal Vdd)
Storage Temperature Range	-55°C to +125°C

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	JESD22-A114, HBM, 3000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition E, 10,000G
Moisture Sensitivity	J-STD-020, MSL 1
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	JESD22-A104, Condition G
Vibration	MIL-STD-883, Method 2007, Condition C, 70G

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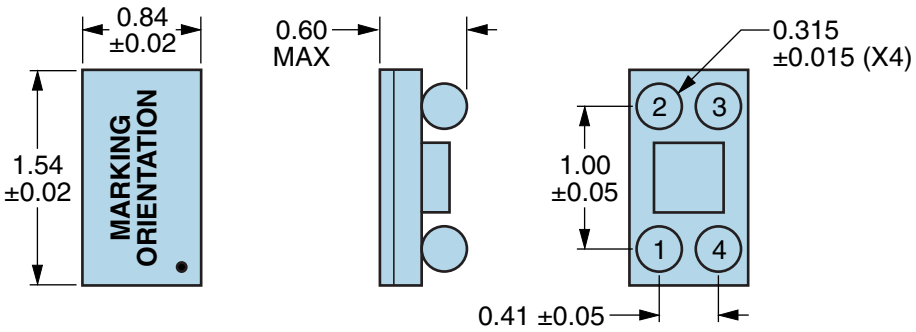
MECHANICAL DIMENSIONS (all dimensions in millimeters)

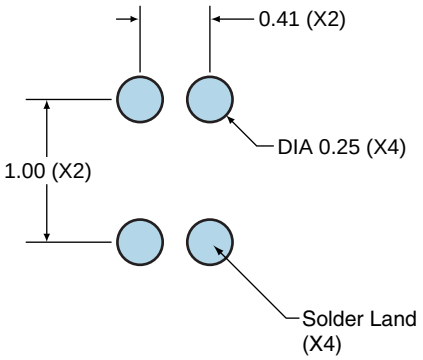


PIN	CONNECTION
1	Ground
2	Output
3	Supply Voltage
4	Ground

LINE	MARKING
1	**XX** *XX=Ecliptek Manufacturing Identifier*
2	**XXX** *XXX=Ecliptek Manufacturing Identifier (continued)*

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

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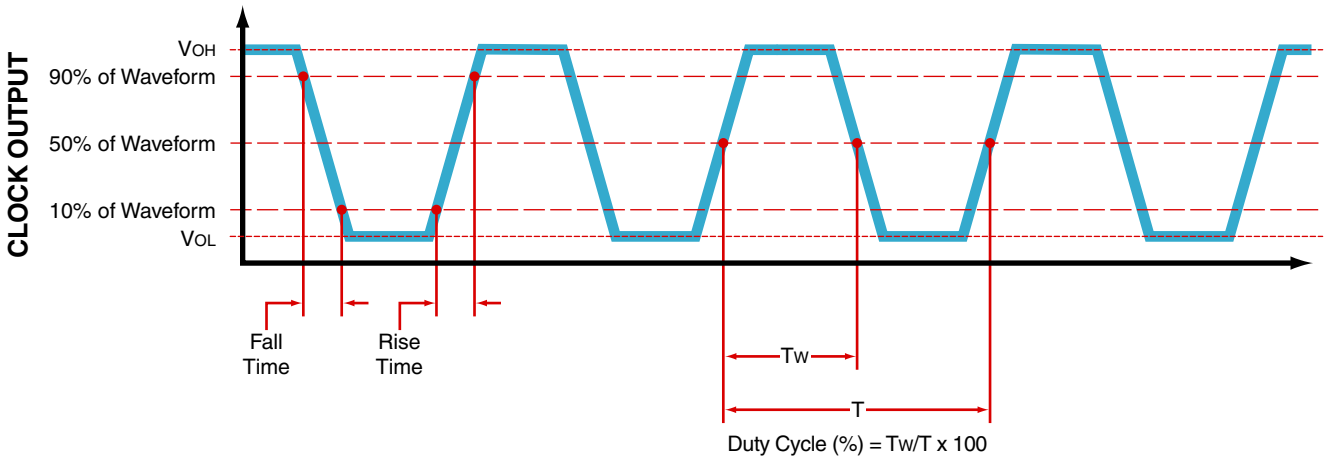
OUTPUT WAVEFORM



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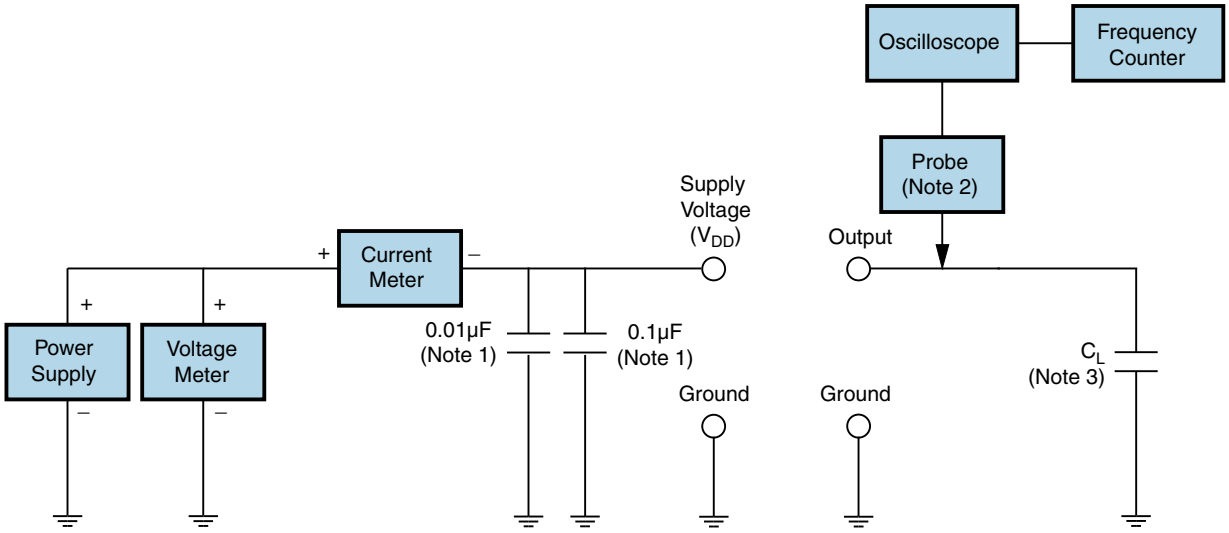
Test Circuit for CMOS Output



Note 1: An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is recommended.
Note 2: A low input capacitance (<12pF), 10X Attentuation Factor, High Impedance (>10Mohms), and High bandwidth (>300MHz) passive probe is recommended.
Note 3: Capacitance value CL includes sum of all probe and fixture capacitance. See applicable specification sheet for 'Load Drive Capability'.

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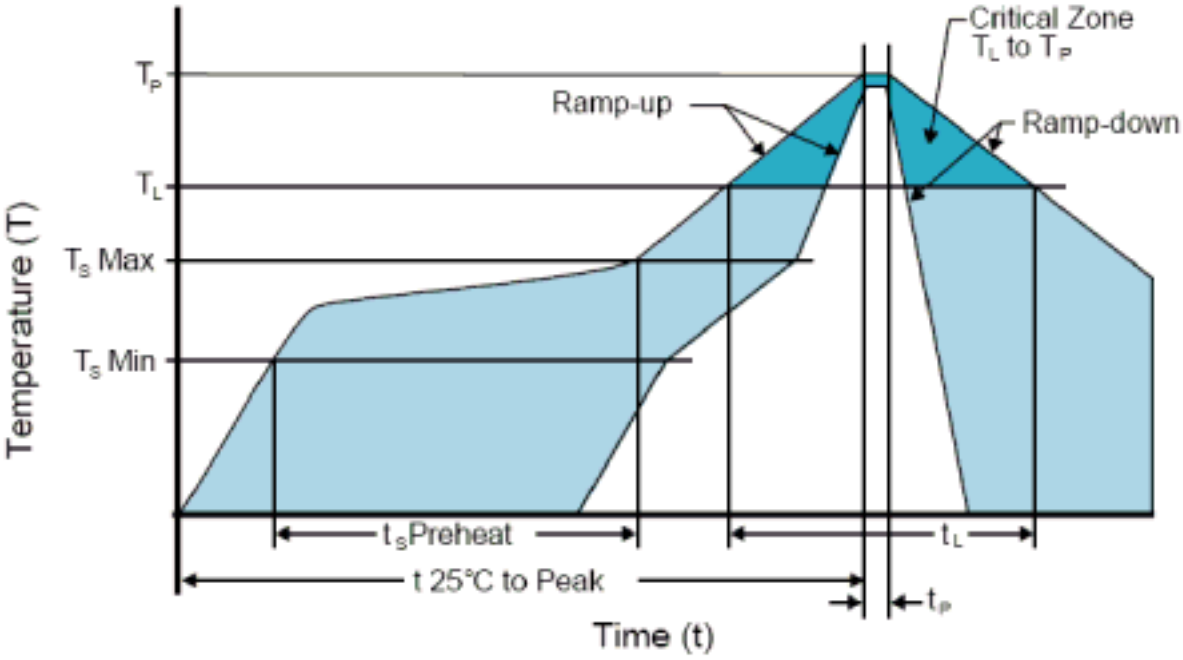
Recommended Solder Reflow Methods



High Temperature Infrared/Convection

T_S MAX to T_L (Ramp-up Rate)	3°C/Second Maximum
Preheat	
- Temperature Minimum (T_S MIN)	150°C
- Temperature Typical (T_S TYP)	175°C
- Temperature Maximum (T_S MAX)	200°C
- Time (t_S MIN)	60 - 180 Seconds
Ramp-up Rate (T_L to T_P)	3°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	217°C
- Time (t_L)	60 - 150 Seconds
Peak Temperature (T_P)	260°C Maximum for 10 Seconds Maximum
Target Peak Temperature (T_P Target)	250°C +0/-5°C
Time within 5°C of actual peak (t_p)	20 - 40 Seconds
Ramp-down Rate	6°C/Second Maximum
Time 25°C to Peak Temperature (t)	8 Minutes Maximum
Moisture Sensitivity Level	Level 1
Additional Notes	Temperature shown are applied to body of device.

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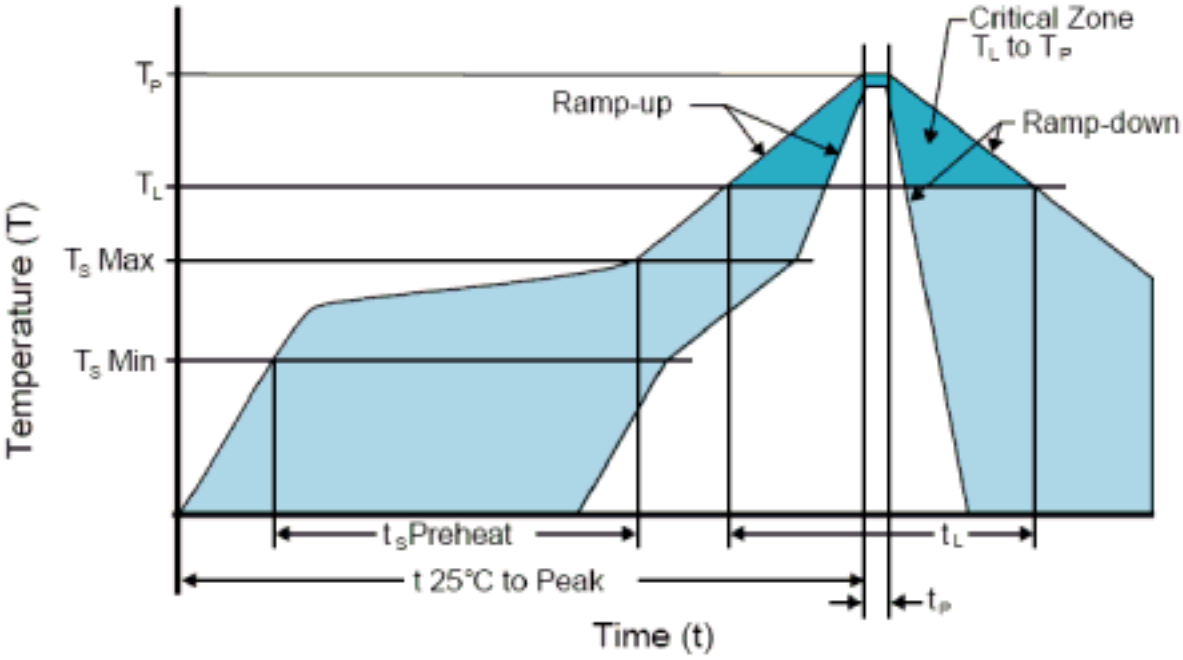
Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_S MAX to T_L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T_S MIN)	N/A
- Temperature Typical (T_S TYP)	150°C
- Temperature Maximum (T_S MAX)	N/A
- Time (t_S MIN)	60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature (T_P Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (t_p)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1
Additional Notes	Temperature shown are applied to body of device.

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperature shown are applied to body of device.)

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- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
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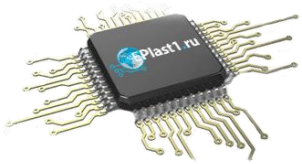
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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